## 2.5V / 3.3V Differential 2:1 Mux Input to 1:6 LVPECL Clock/Data Fanout Buffer / Translator

# Multi–Level Inputs w/ Internal Termination

#### Description

The NB7L585 is a differential 1:6 LVPECL Clock/Data distribution chip featuring a 2:1 Clock/Data input multiplexer with an input select pin. The INx/INx inputs incorporate internal 50  $\Omega$  termination resistors and will accept LVPECL, CML, or LVDS logic levels.

The NB7L585 produces six identical output copies of Clock or Data operating up to 5 GHz or 8 Gb/s, respectively. As such, NB7L585 is ideal for SONET, GigE, Fiber Channel, Backplane and other Clock/Data distribution applications.

The NB7L585 is powered with either 2.5 V or 3.3 V supply and is offered in a low profile 5mm x 5mm 32–pin QFN package.

Application notes, models, and support documentation are available at www.onsemi.com.

The NB7L585 is a member of the GigaComm<sup>™</sup> family of high performance clock products.

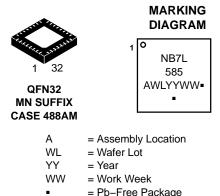
#### Features

- Maximum Input Data Rate > 8 Gb/s
- Data Dependent Jitter < 15 ps
- Maximum Input Clock Frequency > 5 GHz
- Random Clock Jitter < 0.8 ps RMS
- Low Skew 1:6 LVPECL Outputs, 20 ps max
- 2:1 Multi-Level Mux Inputs
- 175 ps Typical Propagation Delay
- 55 ps Typical Rise and Fall Times
- Differential LVPECL Outputs, 800 mV peak-to-peak, typical
- Operating Range:  $V_{CC} = 2.375$  V to 3.6 V with GND = 0 V
- Internal 50 Ω Input Termination Resistors
- VREFAC Reference Output
- QFN-32 Package, 5mm x 5mm
- -40°C to +85°C Ambient Operating Temperature
- These Devices are Pb-Free and are RoHS Compliant



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(Note: Microdot may be in either location)

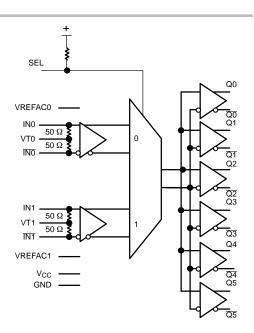
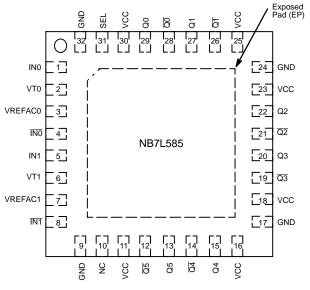


Figure 1. Simplified Block Diagram

**ORDERING INFORMATION** 

See detailed ordering and shipping information on page 8 of this data sheet.



#### **Table 1. INPUT SELECT FUNCTION TABLE**

SEL*	CLK Input Selected
0	INO
1	IN1

\*Defaults HIGH when left open.

Figure 2. Pinout: QFN-	-32 (Top View)
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#### **Table 2. PIN DESCRIPTION**

Pin Number	Pin Name	I/O	Pin Description
1,4 5,8	IN0, <u>IN0</u> IN1, <u>IN1</u>	LVPECL, CML, LVDS Input	Non-inverted, Inverted, Differential Data Inputs internally biased to $V_{\mbox{CC}}/2$
2,6	VT0, VT1		Internal 100 $\Omega$ Center–tapped Termination Pin for IN0 / $\overline{\text{IN0}}$ and IN1 / $\overline{\text{IN1}}$
31	SEL	LVTTL/LVCMOS Input	Input Select pin; LOW for IN0 Inputs, HIGH for IN1 Inputs; defaults HIGH when left open
10	NC	-	No Connect
11, 16, 18 23, 25, 30	V <sub>CC</sub>	-	Positive Supply Voltage. All $V_{CC}$ pins must be connected to the positive power supply for correct DC and AC operation.
29, 28 27, 26 22, 21 20, 19 15, 14 13, 12	$\begin{array}{c} Q0, \overline{Q0}\\ Q1, \overline{Q1}\\ Q2, \overline{Q2}\\ Q3, \overline{Q3}\\ Q4, \overline{Q4}\\ Q5, \overline{Q5}\end{array}$	LVPECL Output	Non-inverted, Inverted Differential Outputs Note 1.
9, 17, 24, 32	GND		Negative Supply Voltage, connected to Ground
3 7	VREFAC0 VREFAC1	-	Output Voltage Reference for Capacitor–Coupled Inputs
_	EP	_	The Exposed Pad (EP) on the QFN–32 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat–sinking conduit. The pad is electrically connected to the die, and must be electrically and thermally connected to GND on the PC board.

In the differential configuration when the input termination pins (VT0, VT1) are connected to a common termination voltage or left open, and if no signal is applied on INn/INn input, then the device will be susceptible to self–oscillation.
 All V<sub>CC</sub> and GND pins must be externally connected to a power supply for proper operation.

#### Table 3. ATTRIBUTES

Characteristic	Value			
ESD Protection	Human Body Model Machine Model	> 2 kV > 200 V		
R <sub>PU</sub> – SEL Input Pullup Resistor		75 kΩ		
Moisture Sensitivity (Note 3)	QFN-32	Level 1		
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in		
Transistor Count	288			
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test				

3. For additional information, see Application Note AND8003/D.

#### **Table 4. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	Positive Power Supply	GND = 0 V		+4.0	V
V <sub>IO</sub>	Input/Output Voltage	GND = 0 V		–0.5 to V <sub>CC</sub> +0.5	V
V <sub>INPP</sub>	Differential Input Voltage  IN – IN			1.89	V
I <sub>IN</sub>	Input Current Through $R_T$ (50 $\Omega$ Resistor)			±40	mA
l <sub>out</sub>	Output Current	Continuous Surge		50 100	mA
IVREFAC	VREFAC Sink or Source Current			±1.5	mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient) (Note 4)	0 lfpm 500 lfpm	QFN32 QFN32	31 27	°C/W
$\theta_{JC}$	Thermal Resistance (Junction-to-Case) (Note 4)		QFN32	12	°C/W
T <sub>sol</sub>	Wave Solder			265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

#### Table 5. DC CHARACTERISTICS POSITIVE LVPECL OUTPUT V<sub>CC</sub> = 2.375 V to 3.6 V; GND = 0 V; T<sub>A</sub> = -40°C to 85°C

			1	r	
Symbol	Characteristic	Min	Тур	Max	Unit
POWER S	UPPLY				
V <sub>CC</sub>	Power Supply Voltage $V_{CC} = 3.3V$ $V_{CC} = 2.5V$	3.0 2.375	3.3 2.5	3.6 2.625	V
lcc	Power Supply Current (Inputs and Outputs Open)		185	225	mA
	Dutputs				
V <sub>OH</sub>	Output HIGH Voltage (Note 6) $ \begin{array}{c} V_{CC} = 3.3 \ V \\ V_{CC} = 2.5 \ V \end{array} $	V <sub>CC</sub> – 1145 2155 1355		V <sub>CC</sub> - 800 2500 1700	mV
V <sub>OL</sub>	Output LOW Voltage (Note 6) $ \begin{array}{c} V_{CC} = 3.3 \ V \\ V_{CC} = 2.5 \ V \end{array} $	V <sub>CC</sub> – 2000 1300 500		V <sub>CC</sub> – 1500 1800 1000	mV
DIFFEREN	NTIAL CLOCK INPUTS DRIVEN SINGLE-ENDED (Note 7) (Figures	5 & 6)			
V <sub>IH</sub>	Single-ended Input HIGH Voltage	V <sub>th</sub> + 100		V <sub>CC</sub>	mV
V <sub>IL</sub>	Single-ended Input LOW Voltage	GND		V <sub>th</sub> – 100	mV
V <sub>th</sub>	Input Threshold Reference Voltage Range (Note 8)			V <sub>CC</sub> –100	mV
V <sub>ISE</sub>	Single-ended Input Voltage (VIH - VIL)			1200	mV
VREFACx	(for Capacitor– Coupled Inputs, Only)				
V <sub>REFAC</sub>	Output Reference Voltage $@100\ \mu\text{A}$ for Capacitor– Coupled Inputs, Only	V <sub>CC</sub> – 1500	V <sub>CC</sub> – 1200	V <sub>CC</sub> – 1000	mV
DIFFEREN	TIAL INPUTS DRIVEN DIFFERENTIALLY (Figures 7 & 8) (Note 9)				
V <sub>IHD</sub>	Differential Input HIGH Voltage (IN, IN)	1200		V <sub>CC</sub>	mV
V <sub>ILD</sub>	Differential Input LOW Voltage (IN , $\overline{IN}$ )	GND		V <sub>IHD</sub> – 100	mV
V <sub>ID</sub>	Differential Input Voltage (IN , $\overline{IN}$ ) (V <sub>IHD</sub> – V <sub>ILD</sub> )	100		1200	mV
V <sub>CMR</sub>	Input Common Mode Range (Differential Configuration, Note 10) (Figure 9)	1050		V <sub>CC</sub> – 50	mV
I <sub>IH</sub>	Input HIGH Current IN/IN (VTIN/VTIN Open)	-150		150	μA
IIL	Input LOW Current IN/IN (VTIN/VTIN Open)			150	μA
CONTROL	- INPUT (SEL Pin)				
V <sub>IH</sub>	Input HIGH Voltage for Control Pin	2.0		V <sub>CC</sub>	mV
V <sub>IL</sub>	Input LOW Voltage for Control Pin	GND		0.8	mV
I <sub>IH</sub>	Input HIGH Current	-150		150	μA
IIL	Input LOW Current	-150		150	μA
TERMINA	TION RESISTORS				
R <sub>TIN</sub>	Internal Input Termination Resistor (Measured from INx to VTx)	45	50	55	Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. Input and output parameters vary 1:1 with V<sub>CC</sub>. 6. LVPECL outputs (Qn/Qn) loaded with 50  $\Omega$  to V<sub>CC</sub> – 2 V for proper operation.

UPECE outputs (chrchr) loaded with 50 ½ to V<sub>CC</sub> – 2 viol proper operation.
 V<sub>th</sub>, V<sub>th</sub>, V<sub>th</sub>, V<sub>tL</sub>, and V<sub>ISE</sub> parameters must be complied with simultaneously.
 V<sub>th</sub>, V<sub>ILD</sub>, V<sub>ID</sub> and V<sub>CMR</sub> parameters must be complied with simultaneously.
 V<sub>HDD</sub>, V<sub>ILD</sub>, V<sub>ID</sub> and V<sub>CMR</sub> parameters must be complied with simultaneously.
 V<sub>HDD</sub>, V<sub>ILD</sub>, V<sub>ID</sub> and V<sub>CMR</sub> parameters must be complied with simultaneously.
 V<sub>CMR</sub> min varies 1:1 with GND, V<sub>CMR</sub> max varies 1:1 with V<sub>CC</sub>. The V<sub>CMR</sub> range is referenced to the most positive side of the differential input signal.

Symbol	Characteristic		Min	Тур	Max	Unit
f <sub>MAX</sub>	Maximum Input Clock Frequency; V <sub>OUTpp</sub> ≥ 400 mV		5	7		GHz
f <sub>DATAMAX</sub>	Maximum Operating Data Rate (PRBS23)		8	10		Gbps
f <sub>SEL</sub>	Maximum Toggle Frequency, SEL		1.0	1.5		GHz
V <sub>OUTpp</sub>	Output Voltage Amplitude (@ V <sub>INPPmin</sub> ) (Note 12) (Figures 8 and 10)	f <sub>in</sub> ≤ 4 GHz f <sub>in</sub> ≤ 5 GHz	550 400	800 650		mV
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay to Differential Outputs, @ 1 GHz, measured at differential crosspoint       IN/IN to Q/Q		125 75	175 200	250 300	ps
t <sub>PLH</sub> TC	Propagation Delay Temperature Coefficient			50		∆fs/°C
tskew	Output – Output skew (within device) (Note 13) Device – Device skew (tpd max – tpdmin)				20 100	ps
t <sub>DC</sub>	Output Clock Duty Cycle (Reference Duty Cycle = 50%)	$f_{in} \le 5.0 \text{ GHz}$	45	50	55	%
$\Phi_{\sf N}$	Phase Noise, f <sub>in</sub> = 1 GHz         10 kHz           100 kHz         100 kHz           1 MHz         10 MHz           20 MHz         40 MHz			-135 -137 -149 -150 -150 -151		dBc
t <sub>∫ΦN</sub>	Integrated Phase Jitter (Figure x) fin = 1 GHz, 12 kHz - 20 MHz Offset (RMS)			36		fs
<sup>ţ</sup> JITTER	RJ – Output Random Jitter (Note 14) DJ – Residual Output Deterministic Jitter (Note 15)	f <sub>in</sub> ≤ 5.0 GHz ≤ 8 Gbps		0.2 5	0.8 15	ps rms ps pk–pk
	Crosstalk Induced Jitter (Adjacent Channel) (Note 17)				0.7	psRMS
V <sub>INPP</sub>	Input Voltage Swing (Differential Configuration) (Note 16)	)	100		1200	mV
t <sub>r,</sub> , t <sub>f</sub>	Output Rise/Fall Times @ 1 GHz (20% – 80%), Q, $\overline{Q}$		25	55	85	ps

	Table 6. AC CHARACTERISTICS $V_{CC}$ = 2.375 V to 3.6 V; GND = 0 V; T <sub>A</sub> = -40°C to 85°C (Note	11)
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NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

11. Measured using a 400 mV pk-pk source, 50% duty cycle clock source. All output loading with external 50  $\Omega$  to V<sub>CC</sub> – 2 V. Input edge rates 40 ps (20% – 80%).

12. Output voltage swing is a single-ended measurement operating in differential mode.

13. Skew is measured between outputs under identical transitions and conditions. Duty cycle skew is defined only for differential operation when the delays are measured from cross-point of the inputs to the crosspoint of the outputs.

14. Additive RMS jitter with 50% duty cycle clock signal.

15. Additive Peak-to-Peak data dependent jitter with input NRZ data at PRBS23.

16. Input voltage swing is a single-ended measurement operating in differential mode.

17. Crosstalk is measured at the output while applying two similar clock frequencies that are asynchronous with respect to each other at the inputs.

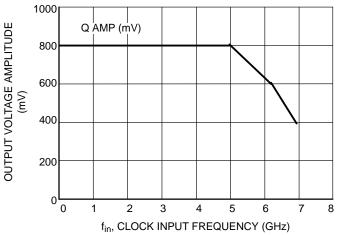
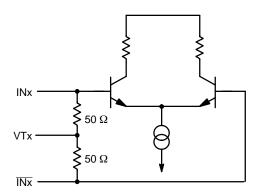
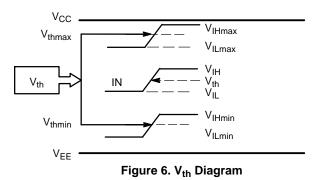


Figure 3. Clock Output Voltage Amplitude (V<sub>OUTpp</sub>) vs. Input Frequency (f<sub>in</sub>) at Ambient Temperature (Typical)







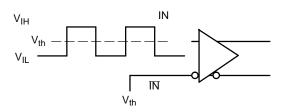
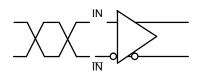


Figure 5. Differential Input Driven Single–Ended





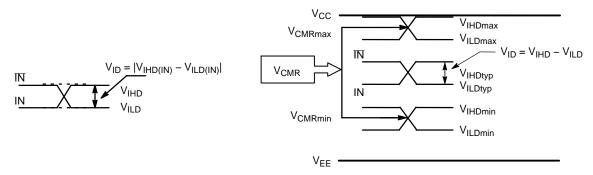
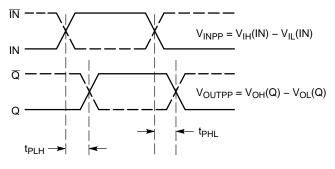
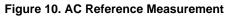


Figure 8. Differential Inputs Driven Differentially

Figure 9. VCMR Diagram





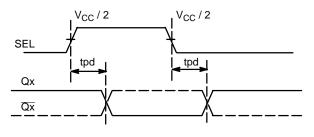
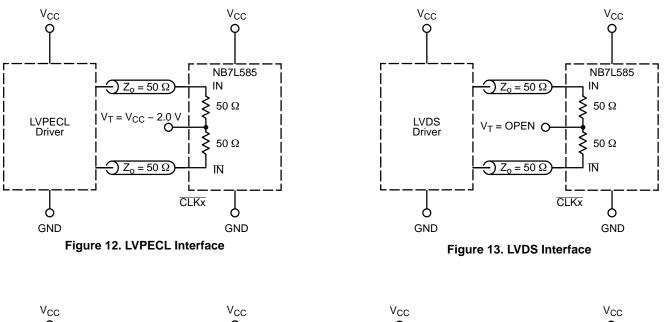


Figure 11. SEL to Qx Timing Diagram



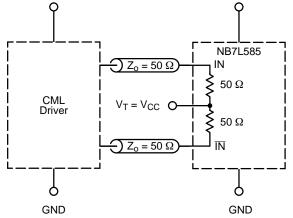


Figure 14. Standard 50  $\Omega$  Load CML Interface

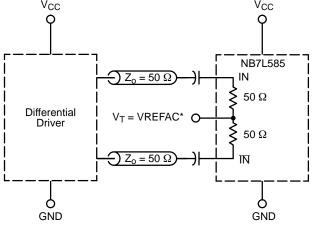
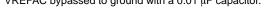
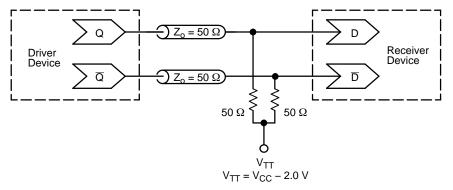
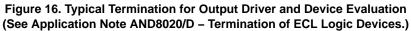


Figure 15. Capacitor–Coupled Differential Interface (V<sub>T</sub> Connected to V<sub>REFAC</sub>) \*VREFAC bypassed to ground with a 0.01 µF capacitor.







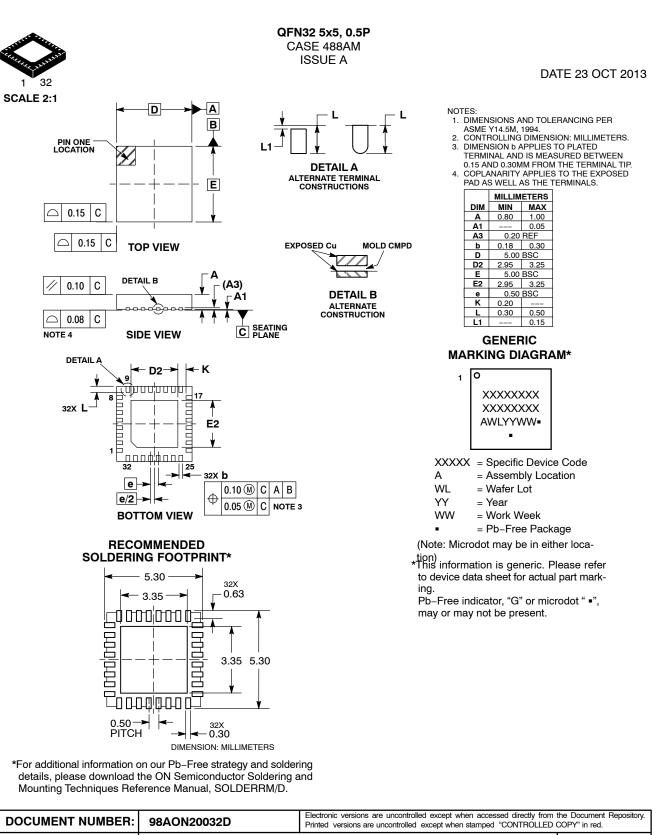
#### **DEVICE ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NB7L585MNG	QFN-32 (Pb-Free)	74 Units / Rail
NB7L585MNR4G	QFN-32 (Pb-Free)	1000 / Tape & Reel
NB7L585MNTWG	QFN-32 (Pb-Free)	1000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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